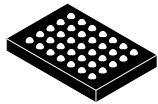


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

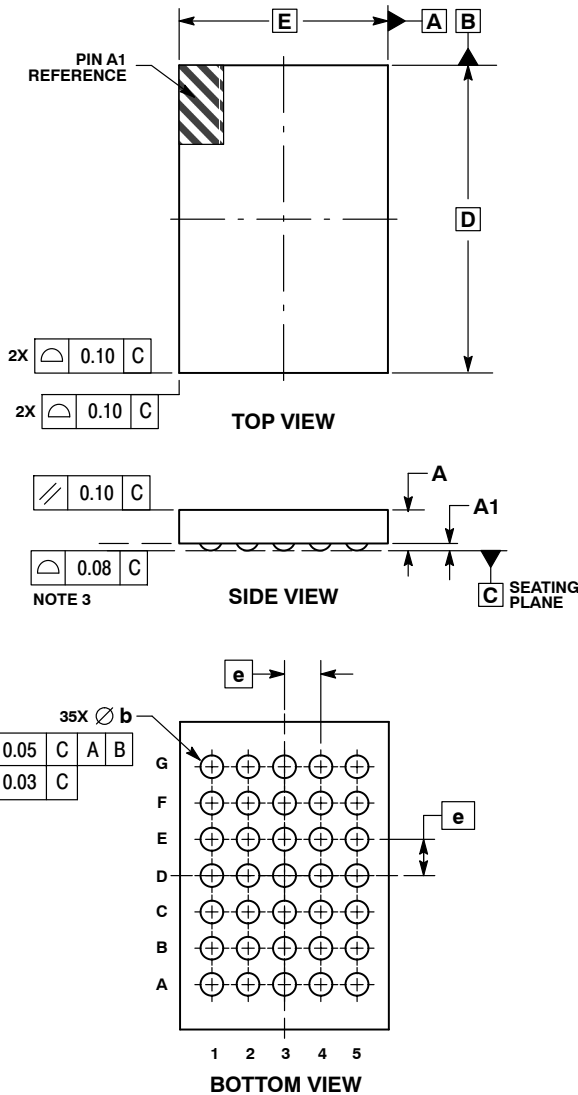
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SCALE 4:1

WLCSP35, 3.39x2.3
CASE 567JG
ISSUE O

DATE 28 OCT 2013

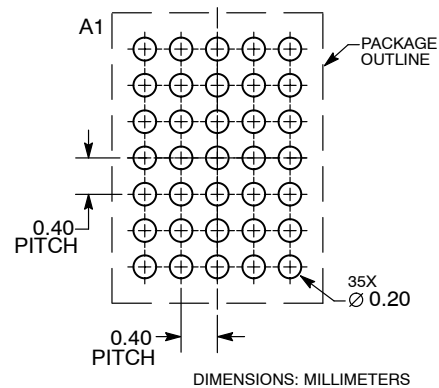


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.45
A1	0.03	0.13
b	0.15	0.25
D	3.39 BSC	
E	2.30 BSC	
e	0.40 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP35, 3.39X2.3	PAGE 1 OF 1

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